

# Outline of Company

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## **Name**

Hirai seimitsu kogyo Corp.

## **President**

Yasuhiro hamada

## **Headquarters**

10-17 2-chome doshin  
Kita-ku Osaka 5300035, Japan  
TEL: +81-6-6351-6712  
FAX: +81-6-6355-2119

## **Establishment**

28th October 1967

## **Capital**

JPN¥ 101,996,000 (US\$ 887,000)

## **Number Of employees**

350

## **Sales items**

Semiconductor related parts  
Lead-frame / stiffener / heat-sink  
Communication related parts  
Lid / seal ring / mask  
LCD (liquid crystal display) parts  
OA / FA related parts  
Others (Assembly fixture parts etc.)  
Ltcc substrate

## **Production location**

Osaka plant  
Ogaki plant  
Kumamoto plant  
Osaka cad center

## **Manufacturing ability** *(For etching process)*

220,000 sheets / month  
(250\*500mm\*0.25mmt conversion)



# History

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**Oct. 1967 Hirai Seimitsu Kogyo Corp. Founded**

Nov. 1977 Ogaki Plant established

Dec. 1980 Osaka Cad Center established

Nov. 1982 Expansion of Ogaki Plant (Plant #2)

Apr. 1984 Expansion of Ogaki Plant (Plant #3)

Mar. 1989 Kumamoto Plant established

Jun. 1990 Expansion of Kumamoto Plant (Plant #2)

Apr. 1993 Capital investment in Jho Machining Inc.

Apr. 1996 Launched LTCC business with NEC

Sep. 1997 Expansion of Kumamoto Plant (Plant #3)

Jan. 2000 Launched Lamination process for t-BGA

Oct. 2001 New Ogaki Plant open (Moving & Expansion)

Ogaki Plant



Kumamoto Plant



Jho Machining Inc.

